

THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD AND SEAL AREA

.050 R NOTCH

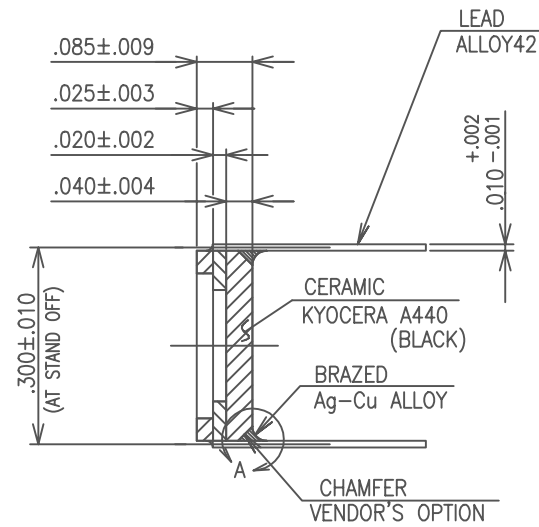
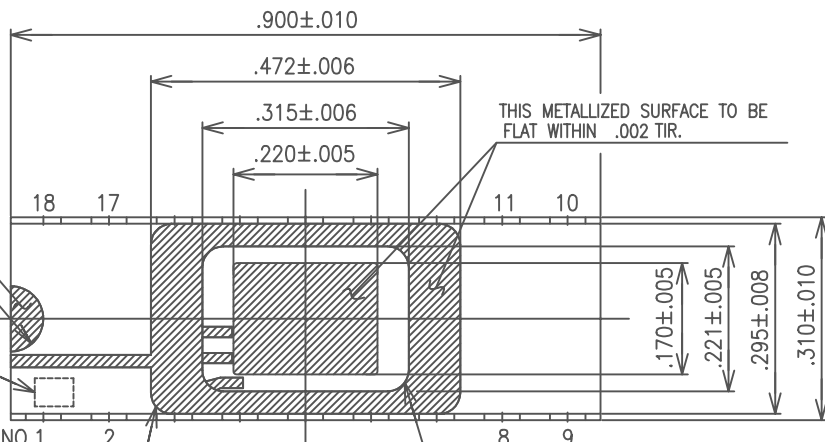
INDEX MARK (SEE TABLE)

PIN NO.1 2 8 9

.032 R TYP.

.020 R TYP.

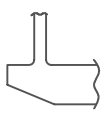
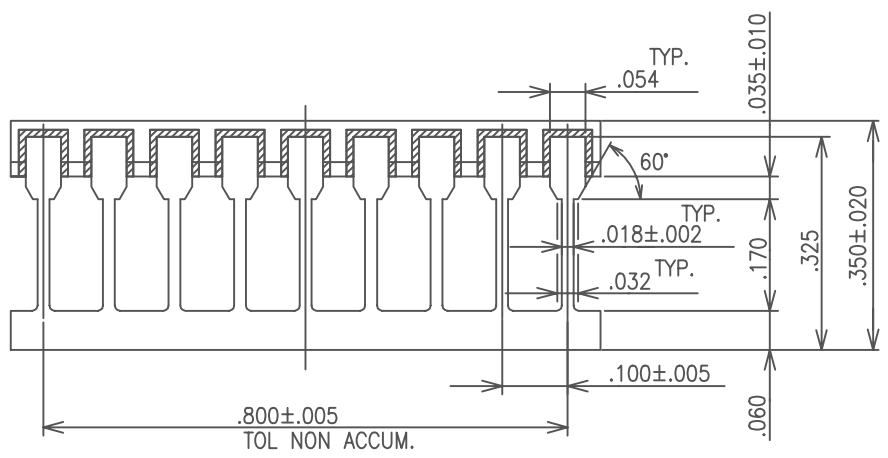
THIS METALLIZED SURFACE TO BE FLAT WITHIN .002 TIR.



PART NO.	INDEX MARK	LEAD TIED DOWN
01		NIL
02		NO.1 ONLY
03		NO.8 ONLY
04		NO.10 ONLY
05		NO.5 ONLY
06		NO.14 ONLY



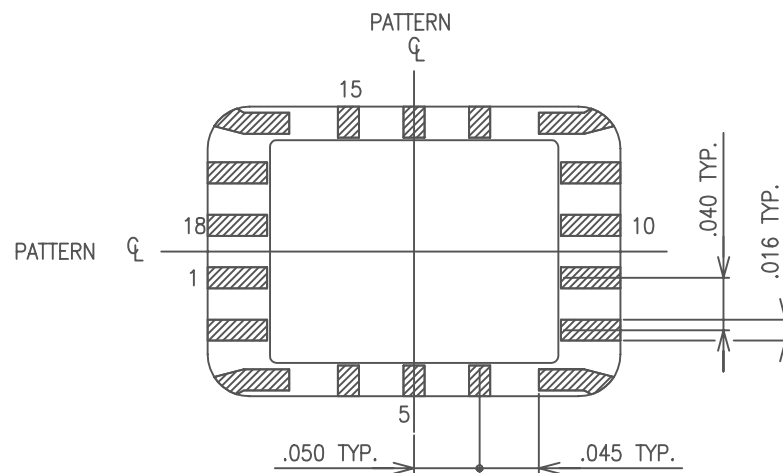
DETAIL-A



VENDOR'S OPTION

SB018H309-6	S=14 D=14
SB018H309-5	S=5 D=5
SB018H309-4	S=10 D=10
SB018H309-3	S=8 D=8
SB018H309-2	S=1 D=1
SB018H309-1	S=0 D=0

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
							18 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	AF/TA	K.M
						SCALE 5/1	MATERIAL AS INDICATED				
							±.005 THIRD ANGLE PROJECTION				
	REDRAWN (CONVERTED CAD DATA)	JAN.31.'95	Y.M	H.S/S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-77309-D			1/2



BONDING PATTERN

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE : 0.20 OHMS MAX.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						18 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	A.F/T.A	K.M	APR.23.'92
						SCALE	MATERIAL				
						10/1					
							THIRD ANGLE PROJECTION				
	△	REDRAWN (CONVERTED CAD DATA)	JAN.31.'95	Y.M	H.S/S.F	T.A		DRAWING NO.			SHEET
		CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN			2/2
								KD-77309-D			